ICS 31.080.01 SLOVENSKÁ TECHNICKÁ NORMA Február 2019

STN	**Polovodičové súčiastky Mechanické a klimatické skúšobné metódy Časť 26: Skúšanie citlivosti na elektrostatický výboj (ESD) Model ľudského tela (HBM)**	**STN EN IEC 60749-26** 35 8799

Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/19

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 60749-26

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Supersedes EN 60749-26:2014

English Version

Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM) (IEC 60749-26:2018)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 26: Essai de sensibilité aux décharges électrostatiques (DES) - Modèle du corps humain (HBM)
(IEC 60749-26:2018)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 26: Prüfung der Empfindlichkeit gegen elektrostatische Entladungen (ESD) - Human Body Model (HBM)
(IEC 60749-26:2018)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Ref. No. EN IEC 60749-26:2018 E

EN IEC 60749-26:2018 (E)

European foreword

The text of document 47/2438/FDIS, future edition 4 of IEC 60749-26, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-26:2018.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2018-11-19
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2021-02-19

This document supersedes EN 60749-26:2014.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60749-26:2018 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60749 (series)	NOTE	Harmonized as EN 60749 (series).
IEC 60749-27	NOTE	Harmonized as EN 60749-27.

IEC 60749-26

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FOREWORD

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International Standard IEC 60749-26 has been prepared by IEC technical committee 47: Semiconductor devices in collaboration with technical committee 101: Electrostatics.

This fourth edition cancels and replaces the third edition published in 2013. This edition constitutes a technical revision. This standard is based upon ANSI/ESDA/JEDEC JS-001-2014. It is used with permission of the copyright holders, ESD Association and JEDEC Solid state Technology Association.

This edition includes the following significant technical changes with respect to the previous edition:

a) a new subclause relating to HBM stressing with a low parasitic simulator is added, together with a test to determine if an HBM simulator is a low parasitic simulator;

b) a new subclause is added for cloned non-supply pins and a new annex is added for testing cloned non-supply pins.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2438/FDIS	47/2454/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 26: Electrostatic discharge (ESD) sensitivity testing – Human body model (HBM)

1 Scope

This part of IEC 60749 establishes the procedure for testing, evaluating, and classifying components and microcircuits according to their susceptibility (sensitivity) to damage or degradation by exposure to a defined human body model (HBM) electrostatic discharge (ESD).

The purpose of this document is to establish a test method that will replicate HBM failures and provide reliable, repeatable HBM ESD test results from tester to tester, regardless of component type. Repeatable data will allow accurate classifications and comparisons of HBM ESD sensitivity levels.

ESD testing of semiconductor devices is selected from this test method, the machine model (MM) test method (see IEC 60749-27) or other ESD test methods in the IEC 60749 series. Unless otherwise specified, this test method is the one selected.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

There are no normative references in this document.